

A B C D

Layer Stack Legend

	Material	Layer	Thickness	Dielectric Material	Type	Gerber	Dk	Weight	Description
1		Top Overlay			Legend	GTO			
	Surface Material	Top Solder	0.035mm	Solder Resist	Solder Mask	GTS	3,5		
	Nickel, Gold	Top Surface Finish	0.004mm		Surface Finish				
	Copper	L 01	0.043mm		Signal	GTL		0.33oz	Base 12um + GalvCu 35um
	Prepreg		0.110mm	FR-4	Dielectric		4,2		
	Copper	L 02	0.018mm		Signal	G1		0.5oz	
	Core		0.300mm	7628	Dielectric		4,2		
	Copper	L 03	0.018mm		Signal	G2		0.5oz	
2	Prepreg		0.180mm	FR-4	Dielectric		4,2		
	Copper	L 04	0.018mm		Signal	G3		0.5oz	
	Core		0.300mm	7628	Dielectric		4,2		
	Copper	L 05	0.018mm		Signal	G4		0.5oz	
	Prepreg		0.110mm	FR-4	Dielectric		4,2		
	Copper	L 06	0.043mm		Signal	GBL		0.33oz	Base 12um + GalvCu 35um
	Nickel, Gold	Bottom Surface Finish	0.004mm		Surface Finish				
	Surface Material	Bottom Solder	0.035mm	Solder Resist	Solder Mask	GBS	3,5		
3		Bottom Overlay			Legend	GBO			

Total thickness: 1.236mm

Transmission Line Structure Table

Impedance Id	Transmission Line	Target Impedance	Calculated Impedance	Trace layer	Narrow Trace Width	Reference layers	Target Tolerance
1	Coated Microstrip	50	49.80	L 01	0.170mm	L 02	10%
2	Offset Stripline	50	50.01	L 03	0.190mm	L 02,L 04	10%
3	Offset Stripline	50	50.01	L 04	0.190mm	L 03,L 05	10%
4	Coated Microstrip	50	49.80	L 06	0.170mm	L 05	10%



Title: TE0890 Layer Stack

A4 Nummer: LS0890 [No Variations] Rev. 02

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